

Please amend the specification as follows:

In the Claims:

1. (amended) A method and system of wire bonding a semiconductor die to a lead, comprising steps of:

attaching a first end of a first bonding wire to a semiconductor die with a ball bond;

attaching a second end of the first bonding wire to an interposer pad with a stitch bond;

attaching a first end of a second bonding wire to the interposer pad with a ball bond; and

attaching the second end of the second bonding wire to the lead with a stitch bond.

A1
Please cancel Claim 3 without prejudice.

8. (amended) A semiconductor device, comprising:

A2
a semiconductor die disposed on a substrate;

a plurality of interposer pads on said substrate;

a plurality of leads on the substrate;

a plurality of bonding wires attached to the semiconductor die with ball bonds and to the leads with stitch bonds, said wires attached to said interposer pads.

A3
11. (amended) The semiconductor device as recited in Claim 8, wherein each of said bonding wires comprises a bonding wire between the semiconductor die and each interposer pad attached to a bonding pad on the semiconductor die with a ball bond and to said interposer pad with a stitch bond and a bonding wire between the interposer pad and the lead attached to the interposer pad with a ball bond and to each lead with a stitch bond.